

L Number	Hits	Search Text	DB	Time stamp
1	1018	(polymer near2 material) with (aluminum copper or (boron near1 nitride) or alumina magnesium brass)	USPAT	2003/02/09 03:49
2	14	((polymer near2 material) with (aluminum copper or (boron near1 nitride) or alumina magnesium brass)) with housing	USPAT	2003/02/09 03:44
4	0	(moldable near1 polymer near2 composition) with housing	USPAT	2003/02/09 03:45
3	32	moldable near1 polymer near2 composition	USPAT	2003/02/09 03:48
5	7472	thermal\$3 near2 conductive near3 material	USPAT	2003/02/09 03:49
6	0	((moldable near1 polymer near2 composition) with housing) with housing	USPAT	2003/02/09 03:49
7	2337	(thermal\$3 near2 conductive near3 material) with (aluminum copper or (boron near1 nitride) or alumina magnesium brass)	USPAT	2003/02/09 03:49
8	33	((thermal\$3 near2 conductive near3 material) with (aluminum copper or (boron near1 nitride) or alumina magnesium brass)) with polymer	USPAT	2003/02/09 04:00
9	1	("4729624").PN.	USPAT	2003/02/09 04:00